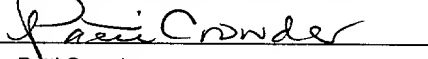


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Patti Crowder

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In the application of:

Benjamin N. Eldridge et al.

Application No.: 09/452,255

Filing Date: May 26, 1995

For: ELECTRICAL CONTACT STRUCTURES  
FORMED BY CONFIGURING A FLEXIBLE  
WIRE TO HAVE A SPRINGABLE SHAPE  
AND OVERCOATING THE WIRE WITH AT  
LEAST ONE LAYER OF A RESILIENT  
CONDUCTIVE MATERIAL, METHODS OF  
MOUNTING THE CONTACT STRUCTURES  
TO ELECTRONIC COMPONENTS, AND  
APPLICATIONS FOR EMPLOYING THE  
CONTACT STRUCTURES

Examiner: C. Arbes

Group Art Unit: 3729

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PATENT APPLICATION SERIAL NO. \_\_\_\_\_

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE  
FEE RECORD SHEET

00/452255

ELECTRICAL CONTACT STRUCTURES FORMED BY CONFIGURING A FLEXIBLE WIRE TO HAVE A SPRINGABLE SHAPE AND OVERCOATING THE WIRE WITH AT LEAST ONE LAYER OF A RESILIENT CONDUCTIVE MATERIAL, METHODS OF MOUNTING THE CONTACT STRUCTURES TO ELECTRONIC COMPONENTS, AND APPLICATIONS FOR EMPLOYING THE CONTACT STRUCTURES

OUTLINE

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